

SPECIFICATION AMENDMENTS:

Please amend the specification as follows:

Page 1, line 2, through line 7, please amend the current paragraph as follows:

--The rights of priority are claimed under 35 USC §119 of U.S. Provisional Application No. 60/413,943, filed September 27, 2003.

BACKGROUND OF THE INVENTION

1. FIELD OF THE INVENTION

The present invention relates to a method of fabricating a dummy wafer, in particular to a dummy wafer that is used in the plasma cleaning and so on.--